

Product Change Notification - KSRA-21BCKN345

Date:

07 May 2019

Product Category:

Linear Op Amps

Affected CPNs:



Notification subject:

CCB 3172 Cancellation Notice: For the qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products for 120K wafer technology available in 8L TDFN (2x3x0.8mm) package at NSEB assembly site

Notification text:

PCN Status:

Cancellation notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

This change would have affected the selected products of the 120K wafer technology available in 8L TDFN (2x3x0.8mm) package NSEB assembly site

Description of Change:

This qualification was originally performed to qualify palladium coated copper with gold flash (CuPdAu) bond wire in selected products for 120K wafer technology available in 8L TDFN (2x3x0.8mm) NSEB assembly site.

Impacts to Data Sheet:

Not applicable

Change Impact:

Not applicable

Reason for Change:

Microchip has decided not to qualify palladium coated copper with gold flash (CuPdAu) bond wire in selected products for 120K wafer technology available in 8L TDFN (2x3x0.8mm) package NSEB assembly site.

Change Implementation Status:

Not applicable

Estimated First Ship Date:

Not applicable

Method to Identify Change:

Not applicable

Revision History:

November 27, 2017: Issued initial notification.

May 07, 2019: Issued cancellation notice for the proposed qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products for 120K wafer technology available in 8L TDFN (2x3x0.8mm) package NSEB assembly site

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN KSRA-21BCKN345_Affected CPN.xlsx



Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

MCP6051T-E/MNY

MCP6061T-E/MNY

MCP6071T-E/MNY

MCP6052T-E/MNY

MCP6062T-E/MNY

MCP6072T-E/MNY

MCP6232T-E/MNY

MCP6402T-E/MNY

MCP6442T-E/MNY

Date: Monday, May 06, 2019